

## IN THE CLAIMS

### Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

### Listing of Claims:

1. (Currently Amended) A capacitor element comprising:

~~an anode~~ a chip body including a porous sintered body formed by sintering valve metal powder into a rectangular parallelepiped having ~~four~~ first to fourth side surfaces, a first end surface and a second end surface which is opposite from the first end surface, and an anode wire ~~fixed to~~ projecting from the first end surface, the first and third surfaces being opposite to each other, the second and fourth surfaces being opposite to each other;

a dielectric film formed on the metal powder of the ~~anode~~ chip body;

a solid electrolyte layer formed on the dielectric film to cover the second end surface and the first to fourth side surfaces of the chip body; and

a cathode-side electrode film formed on the ~~anode~~ chip body via the solid electrolyte film;

~~wherein at least two of four edges of the anode chip body at which the four side surfaces meet the second end surface are rounded or chamfered, the two edges being parallel with each other~~ the first side surface is connected to the second end surface via a first beveled or rounded surface, the third side surface is connected to the second end surface via a second beveled or rounded surface, the second side surface meeting the second end surface along a first edge line, the fourth side surface meeting the second end surface along a second edge line, the solid electrolyte film and the cathode-side electrode film bulging to a greater extent along the first and second edge lines than along the first and second beveled or round surfaces.

2. (Cancelled)

3. (Currently Amended) A method of making a capacitor element of a solid electrolytic capacitor, comprising the steps of:

preparing ~~an anode~~ a chip body including a porous sintered body formed by sintering valve metal powder into a rectangular parallelepiped having ~~four~~ first to fourth side surfaces, a first end surface and a second end surface which is opposite from the first end surface, and an anode wire ~~fixed to~~ projecting from the first end surface, ~~the anode chip body being so formed that at least two of four edges at which the four side surfaces meet the second end surface are chamfered or rounded, the two edges being parallel with each other~~ the first and third surfaces being opposite to each other, the second and fourth surfaces being opposite to each other, the first side surface being connected to the second end surface via a first beveled or rounded surface, the third side surface is connected to the second end surface via a second beveled or rounded surface, the second side surface meeting the second end surface along a first edge line, the fourth side surface meeting the second end surface along a second edge line;

forming a dielectric film on the metal powder of the ~~anode~~ chip body;

forming a solid electrolyte layer to cover the second end surface and the first to fourth side surfaces of the chip body by immersing the ~~anode~~ chip body in an electrolyte solution with the anode wire oriented upward~~[[,]]~~ and pulling the anode chip body from the solution followed by baking the anode chip body; and

forming a cathode-side electrode film of a metal paste on the ~~anode~~ chip body via the solid electrolyte layer;

wherein the formation of the solid electrolyte film and the cathode-side electrode film is performed in a manner such that the solid electrolyte film and the cathode-side electrode film bulge to a greater extent along the first and second edge lines than along the first and second beveled or round surfaces.

4. (Currently Amended) A solid electrolytic capacitor comprising:

an anode lead terminal plate, a cathode lead terminal plate, and a capacitor element arranged between the anode lead terminal plate and the cathode lead terminal plate;

the capacitor element comprising ~~an anode~~ a chip body including a porous sintered body formed by sintering valve metal powder into a rectangular parallelepiped

having ~~four~~ first to fourth side surfaces, a first end surface and a second end surface which is opposite from the first end surface, and an anode wire ~~fixed to projecting from~~ the first end surface, a dielectric film formed on the metal powder of the anode-chip body, a solid electrolyte layer formed on the dielectric film to cover the second end surface and the first to fourth side surfaces of the anode chip body, and a cathode-side electrode film formed on the anode-chip body via the solid electrolyte film, the first and third surfaces being opposite to each other, the second and fourth surfaces being opposite to each other;

the anode wire of the capacitor element being fixed to the anode lead terminal plate, the cathode-side electrode film being electrically connected to the cathode lead terminal plate;

wherein ~~at least two of four edges of the anode chip body at which the four side surfaces meet the second end surface are rounded or chamfered, the two edges being parallel with each other~~ the first side surface being connected to the second end surface via a first beveled or rounded surface, the third side surface is connected to the second end surface via a second beveled or rounded surface, the second side surface meeting the second end surface along a first edge line, the fourth side surface meeting the second end surface along a second edge line, the solid electrolyte film and the cathode-side electrode film bulging to a greater extent along the first and second edge lines than along the first and second beveled or round surfaces.

5. (Currently Amended) The solid electrolytic capacitor according to claim 4, wherein ~~the capacitor element is so arranged that at least two of the four side surfaces of the anode chip body extend in parallel or generally in parallel with obverse surfaces of the two lead terminal plates, the edges at which the two side surfaces meet the second end surface being rounded or chamfered~~ the cathode lead terminal is connected to the cathode-side electrode film on the first side surface of the chip body.